2SC1472(K)

Silicon NPN Epitaxial, Darlington

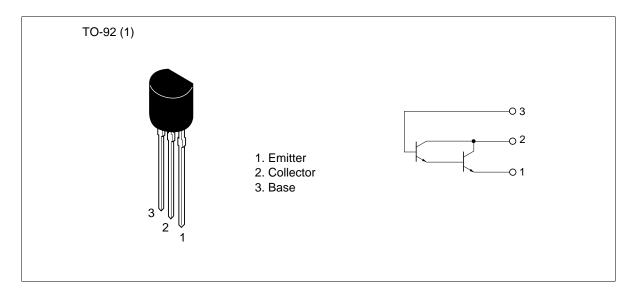
HITACHI

ADE-208-1054 (Z) 1st. Edition Mar. 2001

Application

High gain amplifier

Outline





2SC1472 (K)

Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

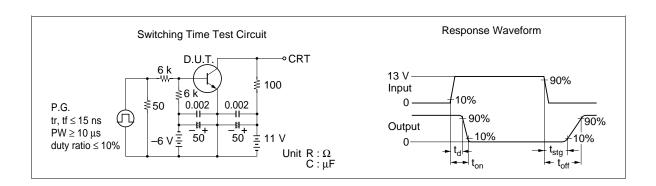
Item	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	40	V
Collector to emitter voltage	V _{CEO}	30	V
Emitter to base voltage	V_{EBO}	10	V
Collector current	I _c	300	mA
Collector peak current	i _{C(peak)}	500	mA
Collector power dissipation	P _c	500	mW
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Electrical Characteristics (Ta = 25°C)

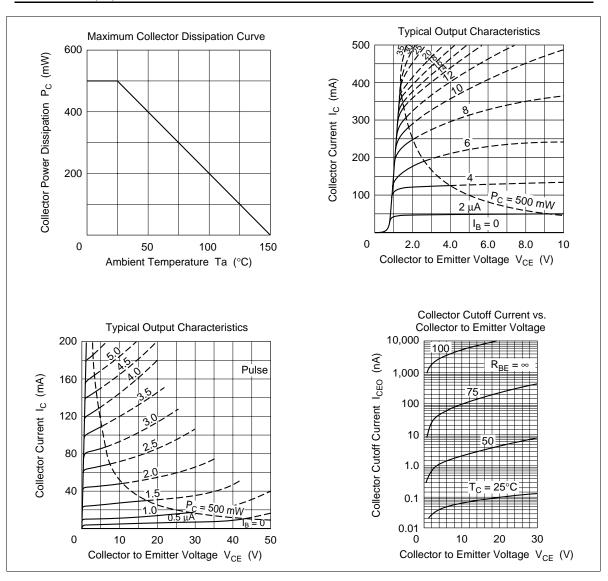
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	30	_	_	V	$I_{C} = 1 \text{ mA}, R_{BE} = \infty$
Collector cutoff current	I _{CBO}	_	_	100	nA	$V_{CB} = 30 \text{ V}, I_{E} = 0$
Emitter cutoff current	I _{EBO}	_	_	100	nA	$V_{EB} = 10 \text{ V}, I_{C} = 0$
DC current transfer ratio	h _{FE1} *1	2000	_	10000	0	$I_{\rm C}$ = 10 mA, $V_{\rm CE}$ = 5 V
	h _{FE2} *1	3000	_	_		$I_C = 100 \text{ mA}, V_{CE} = 5 \text{ V}$ (Pulse Test)
	h _{FE3} *1	3000	_	_		$I_C = 400 \text{ mA}, V_{CE} = 5 \text{ V}$ (Pulse Test)
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	1.5	V	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 0.1 \text{ mA}$
Base to emitter voltage	$V_{BE(sat)}$	_	_	2.0	V	$I_{\rm C} = 100 \text{ mA}, I_{\rm B} = 0.1 \text{ mA}$
Gain bandwidth product	f _T	50	_	_	MHz	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$
Collector output capacitance	Cob	_	_	10	pF	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$
Turn on time	t _{on}	_	60	_	ns	$V_{CC} = 11 \text{ V}$ $I_{C} = 100 \text{ I}_{B1} = 100 \text{ mA}$ $I_{B2} = -I_{B1}$
Turn off time	t _{off}	_	800	_	ns	_
Storage time	t _{stg}	_	350	_	ns	

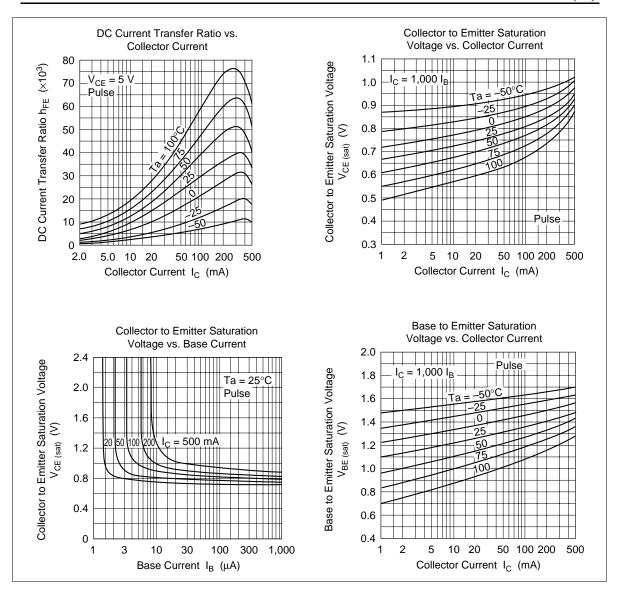
Note: 1. The 2SC1472(K) is grouped by h_{FE} as follows.

	Α	В
h _{FE1}	2000 to 100000	5000 to 100000
h _{FE2}	3000 min	10000 min
h _{FE3}	3000 min	10000 min

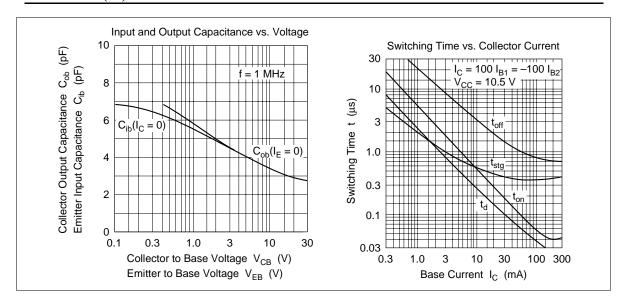


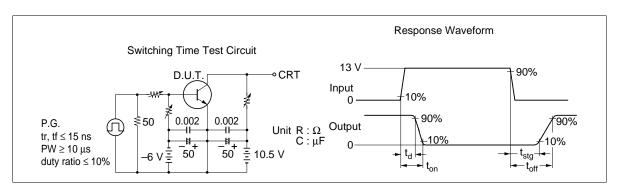
2SC1472 (K)



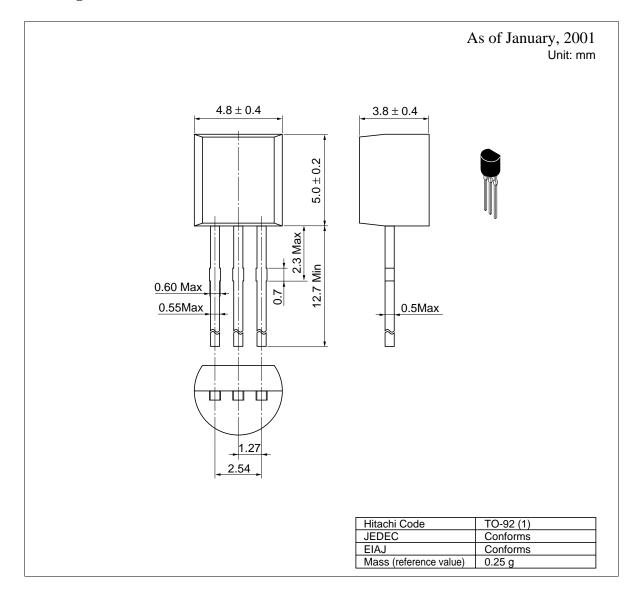


2SC1472 (K)





Package Dimensions



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